



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180223000
Datasheet for OPA838
Information Only

Date: February 26, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA838IDBVT	null
OPA838IDCKT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180223000	PCN Date:	February 26, 2018
Title:	Datasheet for OPA838		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



OPA838

SBOS867A – AUGUST 2017 – REVISED FEBRUARY 2018

Changes from Original (August 2017) to Revision A

Page

• Added OPA837 to the Device Comparison table	4
• Changed Device Comparison table note	4
• Changed format of pin names in pinout drawings in Pin Configuration and Functions section	4
• Added DCK to pinout description in 6-pin SOT-23 and SC70 pinout drawing	4
• Changed I/O column header to "TYPE" in Pin Configuration and Functions section	4
• Added table note to table to define pin types in Pin Configuration and Functions section	4
• Added table note to Absolute Maximum Ratings table	5
• Changed bandwidth for 0.1-dB flatness test condition from $V_{OUT} = 2 V_{PP}$ and $G = 10$ to $V_{OUT} = 200 \text{ mV}_{PP}$ and $G = 6$ in the Electrical Characteristics: $V_S = 5 \text{ V}$ table	6
• Added values for V_{OH} and V_{OL} parameters at $T_A = -40$ to $+125^\circ\text{C}$ in Electrical Characteristics: $V_S = 5 \text{ V}$ table	7
• Changed typical bandwidth for 0.1-dB flatness from 5 MHz to 9 MHz in Electrical Characteristics: $V_S = 3 \text{ V}$ table	8
• Changed bandwidth for 0.1-dB flatness test conditions from $V_{OUT} = 2 V_{PP}$ and $G = 10$ to $V_{OUT} = 200 \text{ mV}_{PP}$ and $G = 6$ in Electrical Characteristics: $V_S = 3 \text{ V}$ table	8
• Added values for V_{OH} and V_{OL} parameters at $T_A = -40$ to $+125^\circ\text{C}$ in Electrical Characteristics: $V_S = 3 \text{ V}$ table	9
• Changed V_O test condition from 20 mV to 200 mV in Figure 5	10
• Changed V_O test condition from 20 mV to 200 mV in Figure 6	10
• Changed test conditions from $V_{OUT} = 2 V_{PP}$, $R_F = 0 \Omega$, $G = 1 \text{ V/V}$ to $R_F = 1 \text{ k}\Omega$, $R_G = 200 \Omega$, $R_L = 2 \text{ k}\Omega$, $G = 6 \text{ V/V}$ in Typical Characteristics: $V_S = 3 \text{ V}$ section	13
• Changed V_O test condition from 20 mV to 200 mV in Figure 23	13
• Changed V_O test condition from 20 mV to 200 mV in Figure 24	13
• Added condition statement to Typical Characteristics: Over Supply Range	16
• Changed Y-axis label from "Disable and V_O (Bipolar supplies)" to "Disable and V_{OUT} (Bipolar Supplies, Volts)" in Figure 51	17
• Changed Y-axis label from "PD and Output Voltages" to "Disable and V_{OUT} (Bipolar Supplies, Volts)" in Figure 52	17
• Deleted 5-V supply and changed the Y-axis label of Figure 57	18

• Changed specification load value from 1-k Ω to 2-k Ω in <i>Output Voltage Range</i> section.....	21
• Changed first paragraph to correct power down logic in <i>Power-Down Operation</i> section.....	21
• Changed image references in <i>Power-Down Operation</i> section	21
• Changed V1 value from 2.5 Ω to 2.5 V in <i>Figure 64</i>	22
• Changed V2 value from 2.5 Ω to -2.5 V in <i>Figure 64</i>	22
• Changed V1 value from 2.5 Ω to 2.5 V, changed V2 value from 2.5 Ω to -2.5 V, and changed R _{OUT} to R _{LOAD} in <i>Figure 66</i>	23
• Changed V _{OUT} input signal from $\pm 0.035 V_{OUT}$ to $\pm 0.35 V_{IN}$ in <i>Figure 68</i>	24
• Changed V1 value from 4.5 Ω to 4.5 V in <i>Figure 70</i>	25
• Changed V _{EE} to ground in <i>Figure 70</i>	25
• Changed V1 value from 3 Ω to 3 V in <i>Figure 72</i>	26
• Updated <i>Single-Supply Op Amp Design Techniques</i> application report link in <i>Device Functional Modes</i> section	27
• Changed "Cs" and "Cf" to "C _s " and "C _f " in <i>Application Information</i> section	34
• Updated <i>Transimpedance Considerations for High-Speed Amplifiers</i> application report link in <i>Detailed Design Procedure</i> section.....	35
• Changed EVM guide link in <i>Layout Guidelines</i> section.....	37

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPA838	SBOS867	SBOS867A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/OPA838>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

OPA838IDBVR	OPA838IDBVT	OPA838IDCKR	OPA838IDCKT
OPA838SIDCKR	OPA838SIDCKT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com